

IN THE SPECIFICATION

Please amend the paragraph beginning at page 6, line 1 as follows:

Reference is made to patent application entitled “~~Arrangements To Increase Structural Rigidity of Semiconductor Package~~ Heat Spreader and Stiffener Having A Stiffener Extension (as amended)” by inventors Hong Xie, Kristopher Frutschy, Koushik Banerjee, and Ajit Sathe filed on ~~a same date as the filing of this patent application~~ September 28, 2001 and published on April 3, 2003, having Application No. 9/964494, and Publication No. US-2003-0062618-A1.